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ULTRATECH ANNOUNCES HB-LED ASIA TECHNOLOGY CENTER IN TAIWAN

Class 1000 Cleanroom to Enable Development of Cost-effective, Scalable HB-LED Manufacturing Processes

SAN JOSE, Calif.—May 11, 2011—Ultratech, Inc. (Nasdaq: UTEK), a leading supplier of lithography and laser-processing systems used to manufacture semiconductor devices and high-brightness LEDs (HB-LEDs), today announced its Asia Technology Center (ATC) in Taiwan. The integrated cleanroom provides the capability for leading-edge process development and in-depth demonstrations of Ultratech’s Sapphire 100 lithography system, designed for customers in the emerging HB-LED market. To further support the company’s Singapore international operations facility, announced last year, this center will enable cost-effective, leading-edge process development that can be transferred between sites or across Ultratech’s large customer base throughout the Pacific Rim. Scheduled to open in the second half of 2011, the ATC furthers Ultratech’s ongoing commitment to meet its international customers’ needs with advanced technology solutions at the lowest cost-of-ownership.

Ultratech Chairman and CEO Arthur W. Zafiropoulo said, “With many of our customers located in the Pacific Rim, opening our Asia Technology Center in Taiwan enables us to work with leading companies to develop processes and lithography equipment advances to reduce the cost of manufacturing LEDs. In addition, the facility will be used to provide yield research as well as low-cost patterning solutions. Ultratech remains vigilant in its search for ways to provide low-cost solutions to support the significant growth in the HB-LED markets. We look forward to leveraging our Asia Technology Center to help speed the development of cost-effective lithography processes to support our customers’ product and technology roadmaps for new and emerging markets.”

Ultratech’s Asia Technology Center (ATC) is located in Taiwan:
FL-1, No.26
Taiyuan Street, Chupei Li, Hsinchu City,
Hsinchu County
Taiwan 302, R.O.C.

Sapphire 100 Lithography System

Building upon the cost and performance advantages of the highly reliable 1500 platform, the next-generation Sapphire 100 system provides the best operational flexibility due to the fundamental benefits of the 1X lens design and market-specific technology options for high-volume, HB-LED manufacturing. The Sapphire 100 was specifically designed to meet the wide range of lithography needs and cost advantages for the HB-LED manufacturing industry.

Certain of the statements contained herein, which are not historical facts and which can generally be identified by words such as “anticipates,” “expects,” “thinks,” “intends,” “will,” “could,” “believes,” “estimates,” “continue,” and similar expressions, are forward-looking statements under Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended, that involve risks and uncertainties, such as risks related to timing, delays, deferrals and cancellations of orders by customers, including as a result of semiconductor manufacturing capacity as well as our customers’ financial condition and demand for semiconductors; demand for consumer devices; industry growth within the company’s served markets; continued delivery of financial performance and value; cyclicalities in the semiconductor and nanotechnology industries; general economic and financial market conditions including impact on capital spending, as well as difficulty in predicting changes in such conditions; rapid technological change and the importance of timely product introductions; customer concentration; our dependence on new product introductions and market acceptance of new products and enhanced versions of our existing products; lengthy sales cycles, including the timing of system installations and acceptances; lengthy and costly development cycles for laser-processing and lithography technologies and applications; integration, development and associated expenses of the laser processing operation; pricing pressures and product discounts; high degree of industry competition; intellectual property matters; changes in pricing by us, our competitors or suppliers; international sales and operations; timing of new product announcements and releases by us or our competitors; ability to volume produce systems and meet customer requirements; sole or limited sources of supply; effect of capital market fluctuations on our investment portfolio; ability and resulting costs to attract or retain sufficient personnel to achieve our targets for a particular period; dilutive effect of employee stock option grants on net income per share, which is largely dependent upon our achieving and maintaining profitability and the market price of our stock; mix of products sold; outcome of litigation; manufacturing variances and production levels; timing and degree of success of technologies licensed to outside parties; product concentration and lack of product revenue diversification; inventory obsolescence; asset impairment; changes to financial accounting standards; effects of certain anti-takeover provisions; future acquisitions; volatility of stock price; foreign government regulations and restrictions; business interruptions due to natural disasters or utility failures; environmental regulations; and any adverse effects of terrorist attacks in the United States or elsewhere, or government responses thereto, or military actions in Iraq, Afghanistan and elsewhere, on the economy, in general, or on our business in particular. Such risks and uncertainties are described in Ultratech’s SEC reports including its Annual Report on Form 10-K filed for the year ended December 31, 2010 and Quarterly Report on Form 10Q for the quarter ended April 2, 2011. Due to these and additional factors, the statements, historical results and percentage relationships set forth herein are not necessarily indicative of the results of operations for any future period. These forward-looking statements are based on management’s current beliefs and expectations, some or all of which may prove to be inaccurate, and which may change. We undertake no obligation to revise or update any forward-looking statements to affect any event or circumstance that may arise after the date of this release.

About Ultratech: Ultratech, Inc. (Nasdaq: UTEK) designs, manufactures and markets photolithography and laser processing equipment. Founded in 1979, the company’s market-leading advanced lithography products deliver high throughput and production yields at a low, overall cost of ownership for bump packaging of integrated circuits and high-brightness LEDs (HB-LEDs). A pioneer of laser processing, Ultratech developed laser spike anneal technology, which increases device yield, improves transistor performance and enables the progression of Moore’s Law for 45-nm and below production of state-of-the-art consumer electronics. Visit Ultratech online at: www.ultratech.com. (UTEK-G)

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